

## RELIABILITY TEST DATA

Product name : S-25C040A0I-T8TxU

Package type : 8Pin-TSSOP

No.	Test item	Test Condition	Test Time	r/n
1	High Temperature Operation	Ta=125 °C V <sub>CC</sub> =Vopr max.	1000 h	0/22
2	Write/Erase Cycle	Ta=25 °C V <sub>CC</sub> =Vopr max.	1×10 <sup>6</sup> cycles	0/22
3	High Temperature Bias	Ta=125 °C V <sub>CC</sub> =Vabs max.×0.9	1000 h	0/22
4	#1 Temperature Humidity Bias	Ta=85 °C RH=85 % V <sub>CC</sub> =Vabs max.×0.9	1000 h	0/22
5	#1 Un-saturated Pressure Cooker Bias	Ta=125 °C RH=85 % P=2×10 <sup>5</sup> Pa V <sub>CC</sub> =Vabs max.×0.9	100 h	0/22
6	High Temperature Storage	Tstg max.=150 °C	1000 h	0/22
7	Low Temperature Storage	Tstg min.=−65 °C	1000 h	0/22
8	#1 Temperature Cycle (Gas phase)	Tstg max.=150 °C , Tstg min.=−65 °C ( 30 min each )	200 cycles	0/22
9	#1 Thermal Shock (Liquid phase)	Tstg max.=150 °C , Tstg min.=−65 °C ( 5 min each )	100 cycles	0/22
10	#1 Resistance to soldering heat - 1 (reflow)	T=260 °C , 10 s	3 times	0/22
11	#1 Resistance to soldering heat - 2 (Solder iron)	T=380 °C , 5 s	Twice	0/22
12	#2 Solderability	T=230 °C Solder material ; Sn-3.0Ag-0.5Cu	3 s	0/11
13	Whisker - 1 (Room Temperature Storage)	Ta=25±3 °C RH=40~70% criteria ; Whisker should be less than 50μm	3 months	0/10
14	Whisker - 2 (Temperature Cycle)	Tstg max.=85 °C , Tstg min.=−40 °C (30 min each) criteria ; Whisker should be less than 50μm	1000 cycles	0/10
15	Whisker - 3 (Temperature Humidity Storage)	Ta=60 °C RH=93 % criteria ; Whisker should be less than 50μm	2000 h	0/10
16	Solder Joint Reliability (Temperature Cycle + shear test)	Tstg max.=125 °C , Tstg min.=−40 °C (30 min each) Solder material ; Sn-3.0Ag-0.5Cu criteria ;After temperature cycle test, keep strength for shear stress more than the 50 % of initial mean value.	2000 cycles	0/5
17	Lead Strength (Pull test)	Pull force ; 1.0 N	30 s	0/11
18	Lead Strength (Bending test)	Load ;0.5 N 45 degree Bend a lead	Twice	0/11

19	ESD - 1 (Human Body Model)	V=±2000 V C=100 pF R=1.5 kΩ Ref. To V <sub>CC</sub> / GND (5units for each direction)	5 pulses	0/20
20	ESD - 2 (Machine Model)	V=±200 V C=200 pF R=0 Ω Ref. To V <sub>CC</sub> / GND (5units for each direction)	3 pulses	0/20
21	Latch Up	±100 mA (V <sub>CLAMP</sub> = Vopr max.) 10 ms pulse V <sub>CC</sub> =Vopr max.	1 pulse	0/5

Remark : Vabs max. = Absolute maximum voltage , Vopr max. =Maximum operation voltage

# : Each test designated # is performed after Pre-Treatment finished.

Pre-Treatment consists of High Temperature Storage , Temperature Humidity Storage and Soldering Heat. (See the table below.)

Pre Treatment (#1)		
High Temp. Storage	Temperature Humidity Storage	Soldering Heat
Ta=125 °C t=24 h	Ta=85 °C RH=85 % t=168 h	Infrared Reflow 3 times T=260 °C t=10 s

Pre Treatment (#2)		
High Temp. Storage	Temperature Humidity Storage	Soldering Heat
Ta=125 °C t=24 h	Ta=105 °C RH=100 % t=8 h	—